

To: University of Pennsylvania

ELS-7500EX

Electron Beam Lithography System

On-site inspection report

Inspection Date : 2008/January/_____

Serial No. : H34 – 085

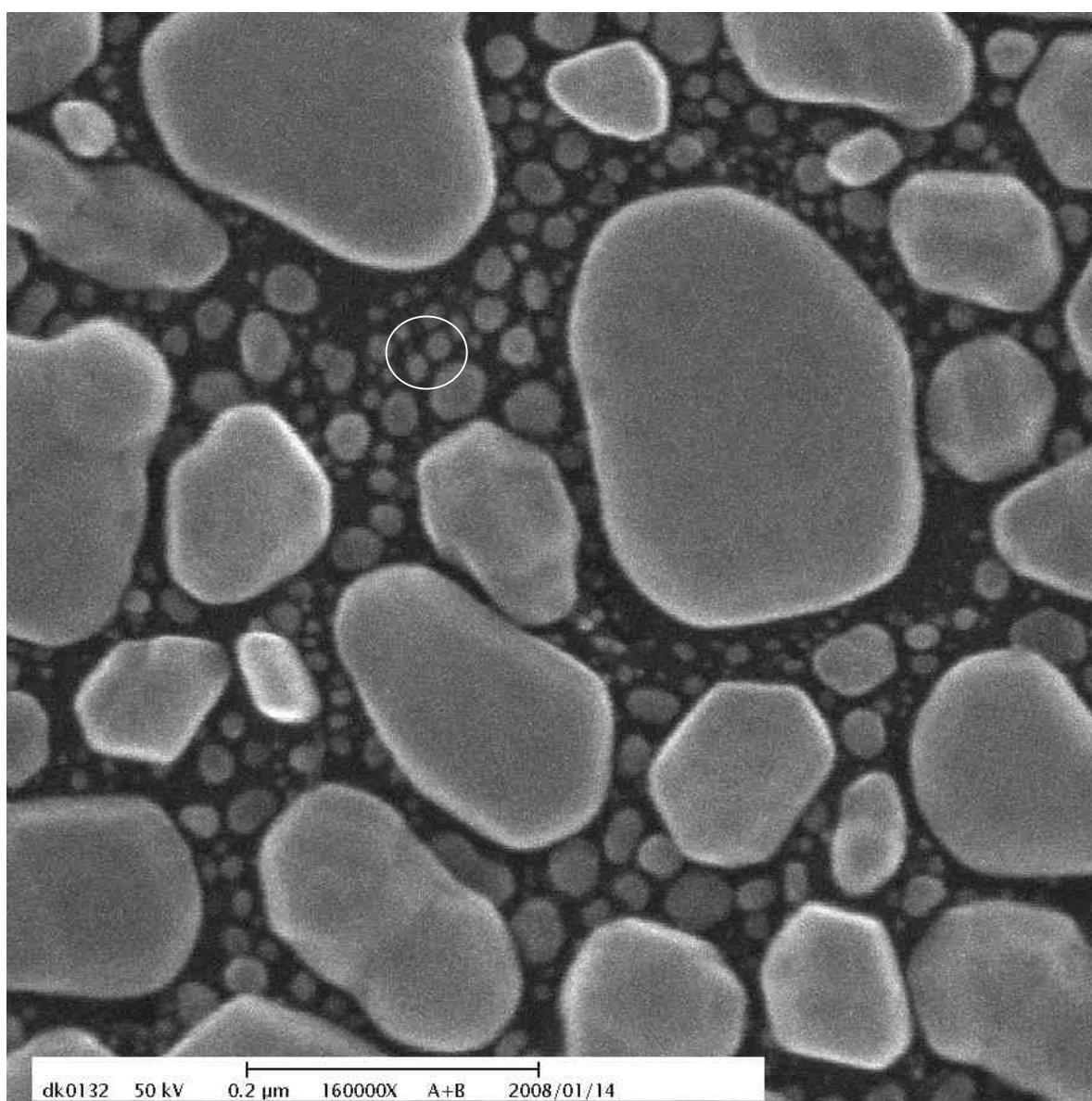
ELIONIX INC.

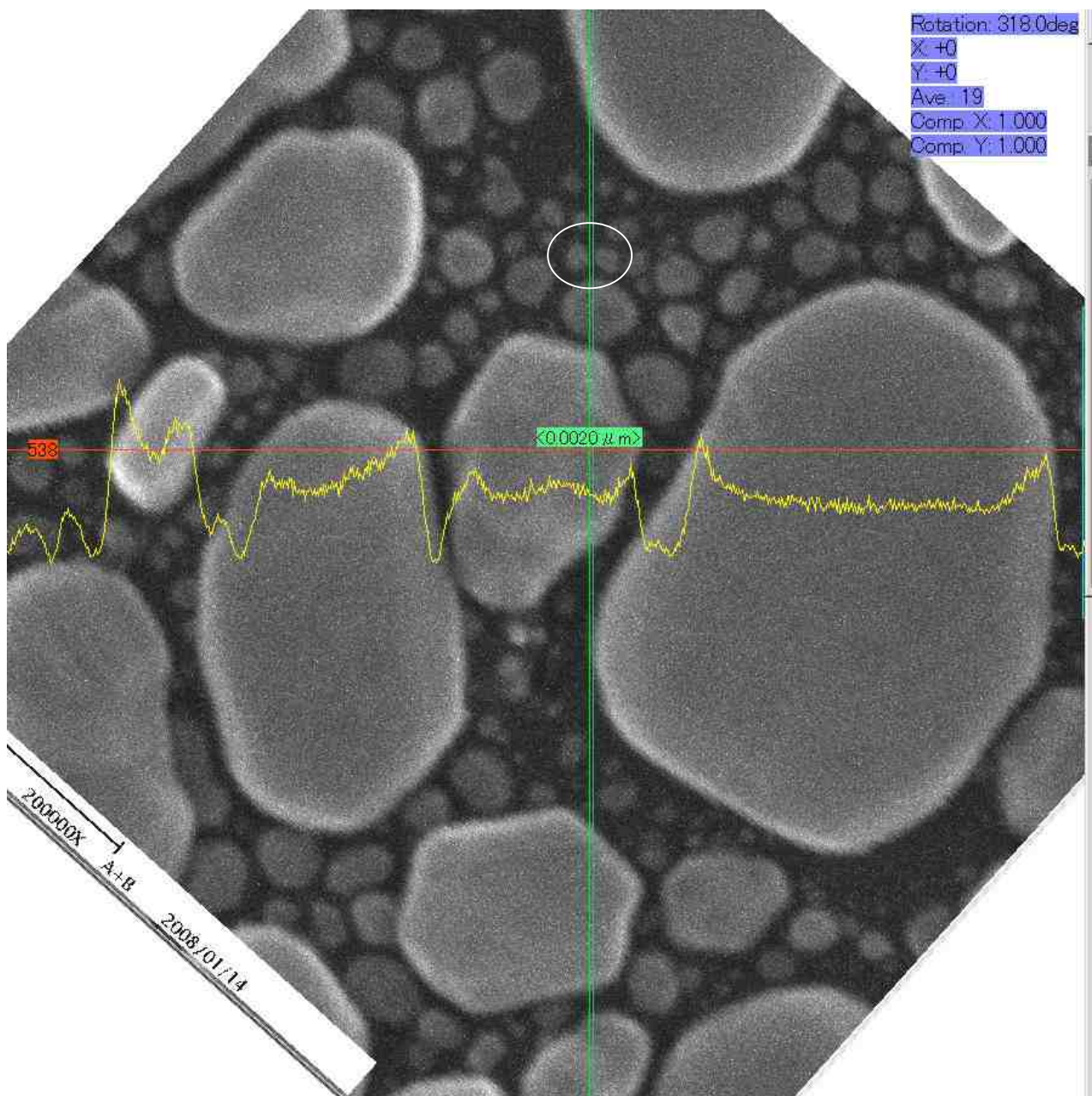
Director Engineering	Confirmation	Inspector

	Inspection Item	Standard	Judgment
1	Secondary electron image	Photo confirming 2nm at $\times 160,000$, Which accompanies Inspection Results	<u>pass</u>
2	Accelerating voltage	5 ~ 50 kV	<u>pass</u>
3	Vacuum degree of specimen chamber	7×10^{-4} Pa or less	<u>pass</u>
4	Power failure	Valve lock, and power OFF Turbo molecular pump rotation falls and stops.	<u>pass</u>
5	Electron gun chamber vacuum deteriorated	Electron gun power supply OFF	<u>pass</u>
6	Specimen chamber vacuum deteriorated	Alarm buzzer, and isolation valve closed	<u>pass</u>
7	Low N ₂ gas pressure	Alarm buzzer	<u>pass</u>
8	Low compressed air pressure	Alarm buzzer, and valve lock. Turbo molecular pump rotation falls and stops.	<u>pass</u>
9	Turbo molecular pump failure	Alarm buzzer, and valve lock.	<u>pass</u>

Secondary Electron Image

Vacc : 50 kV
Magnification : $\times 160,000$
Objective aperture : 0.06 mm
Beam current code : 48396 / 65535
CL2 code : 55000 / 65535
Beam current : 20 pA





Drawing

- (1) Line width 10nm
- (2) 0.1 μ m Line & Space
- (3) Multi test pattern
- (4) Field stitching

Judgment
<u>pass</u>

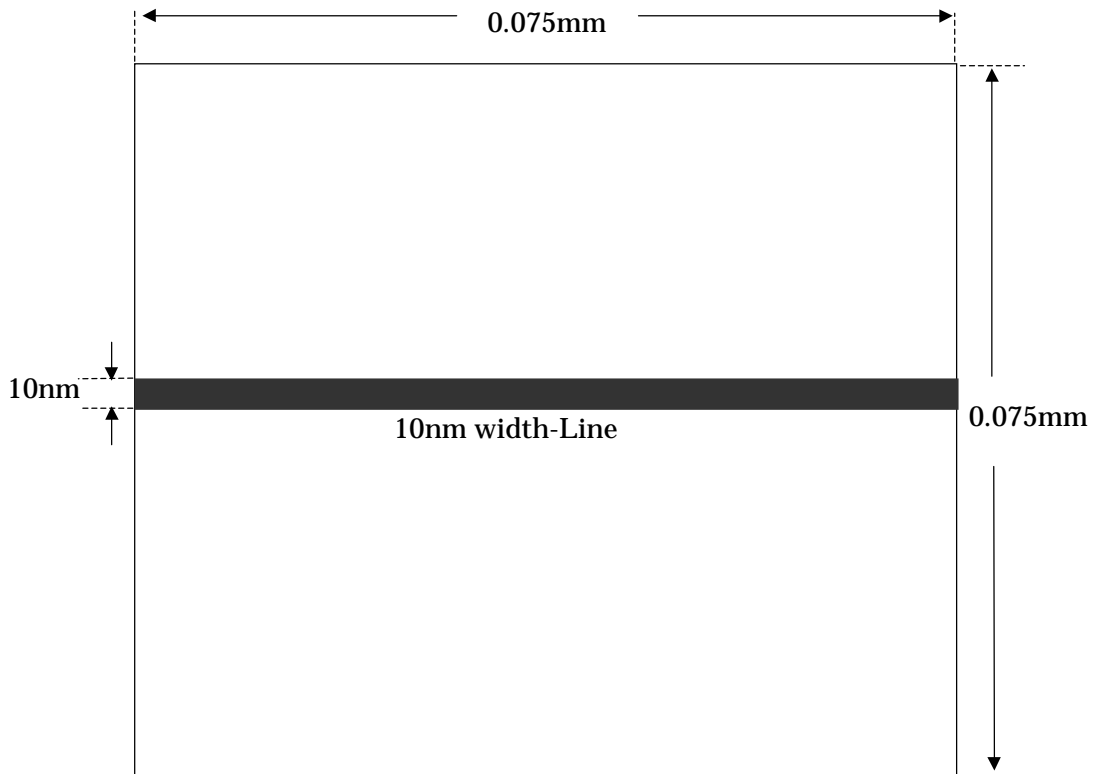
Options

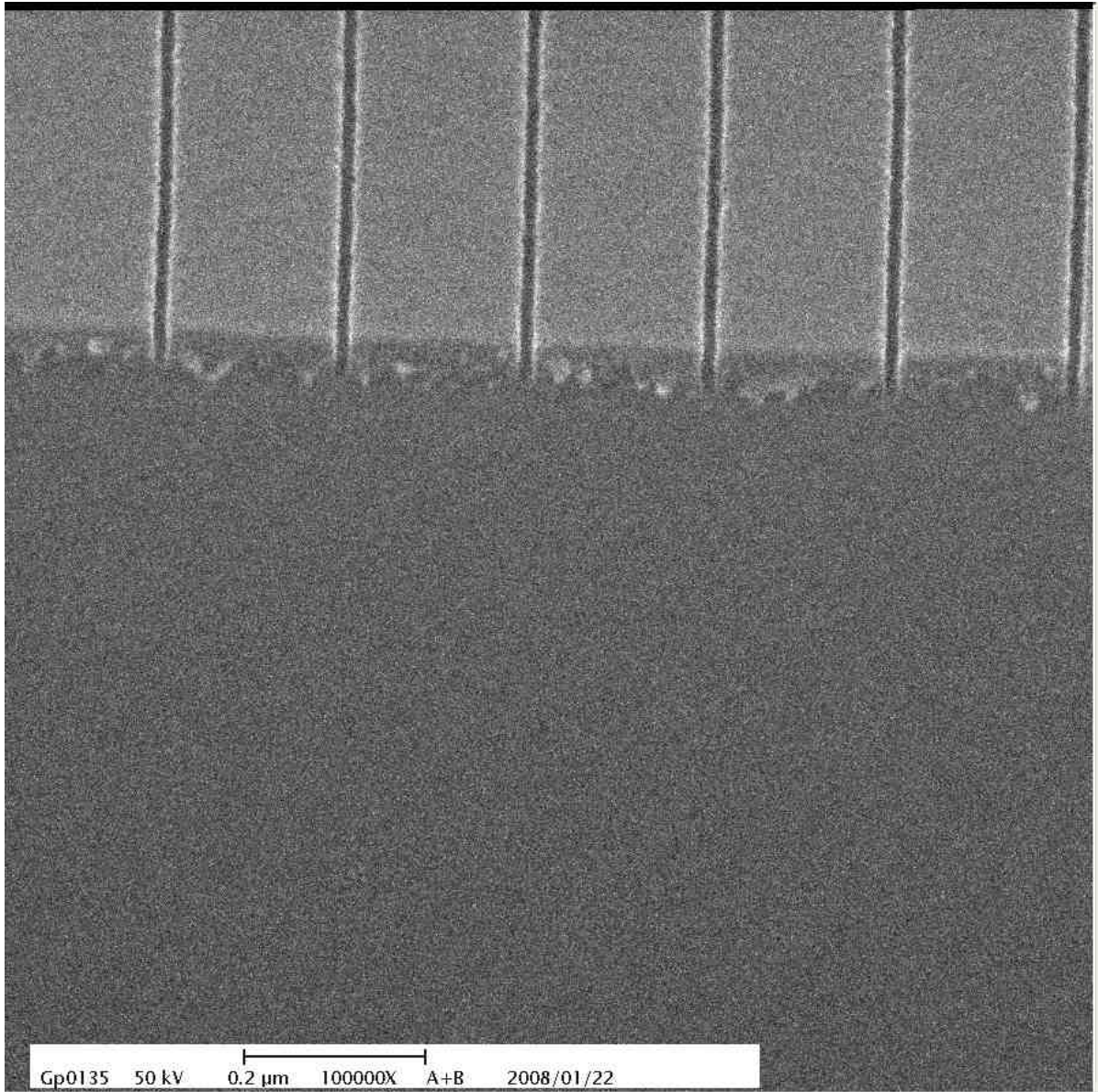
- Overlay
- Circle pattern generator
- Raster scan
- Spot
- Fine step field size modulation
- Function pattern
- DXF,GDS data conversion

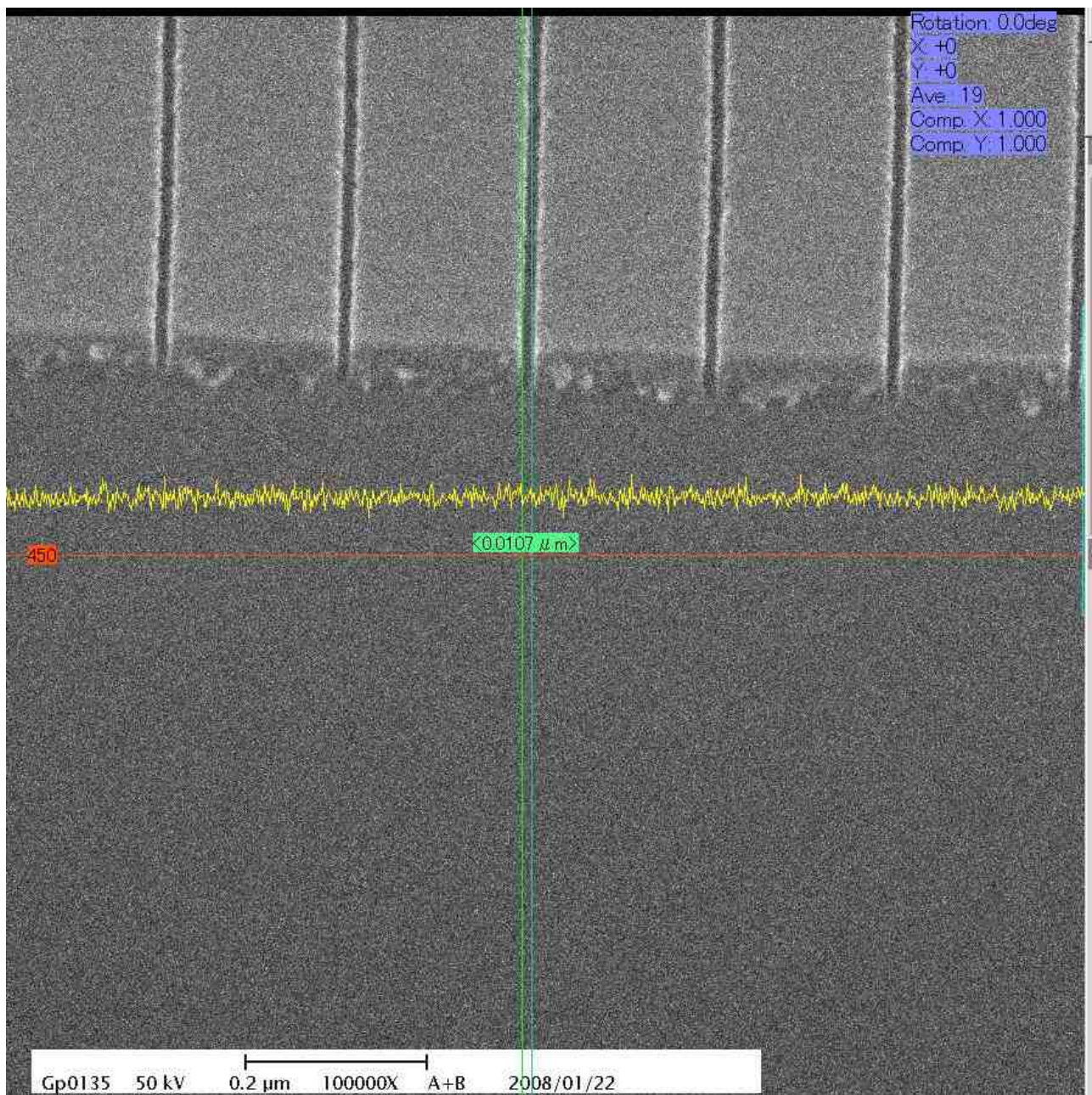
Judgment
<u>pass</u>

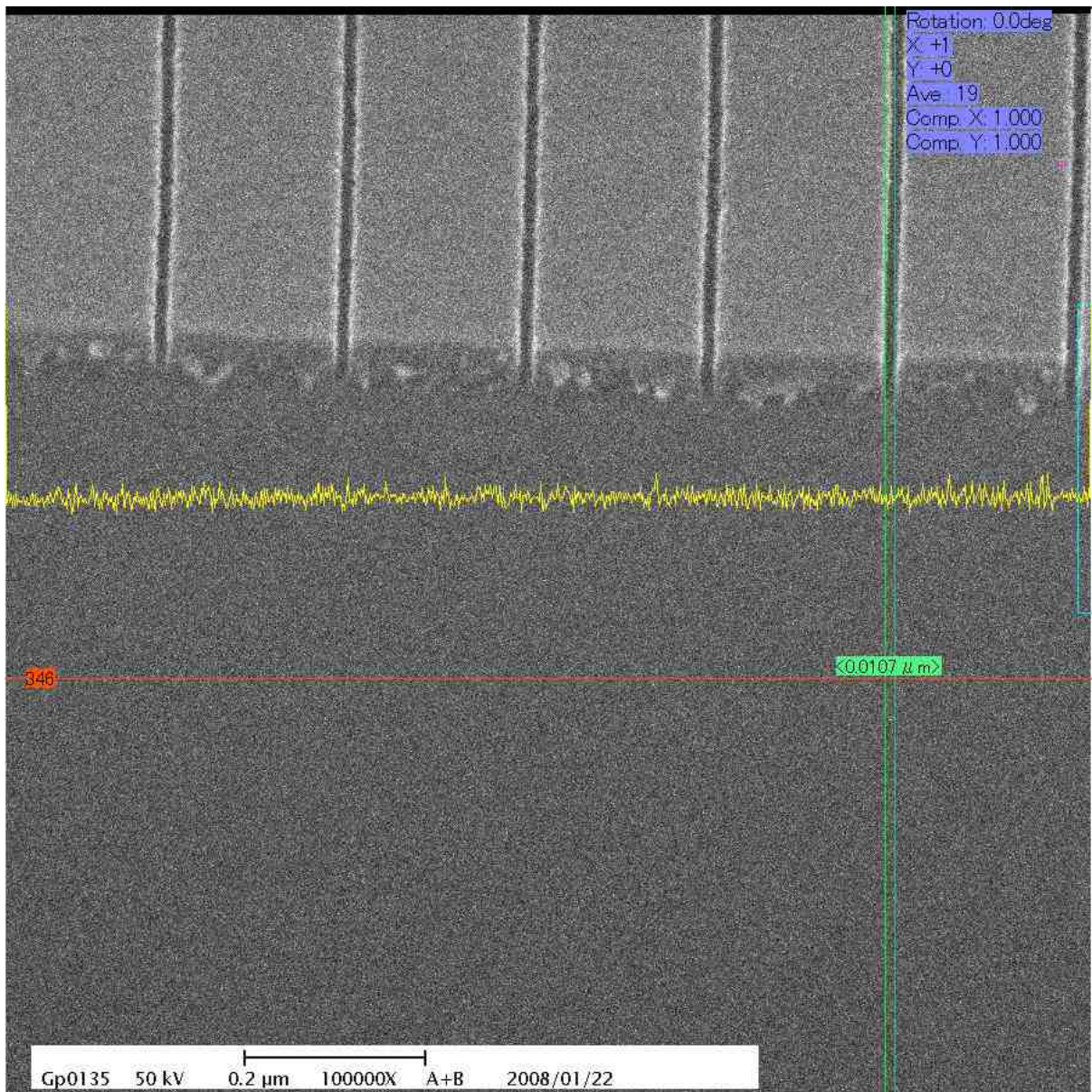
Line width 10nm

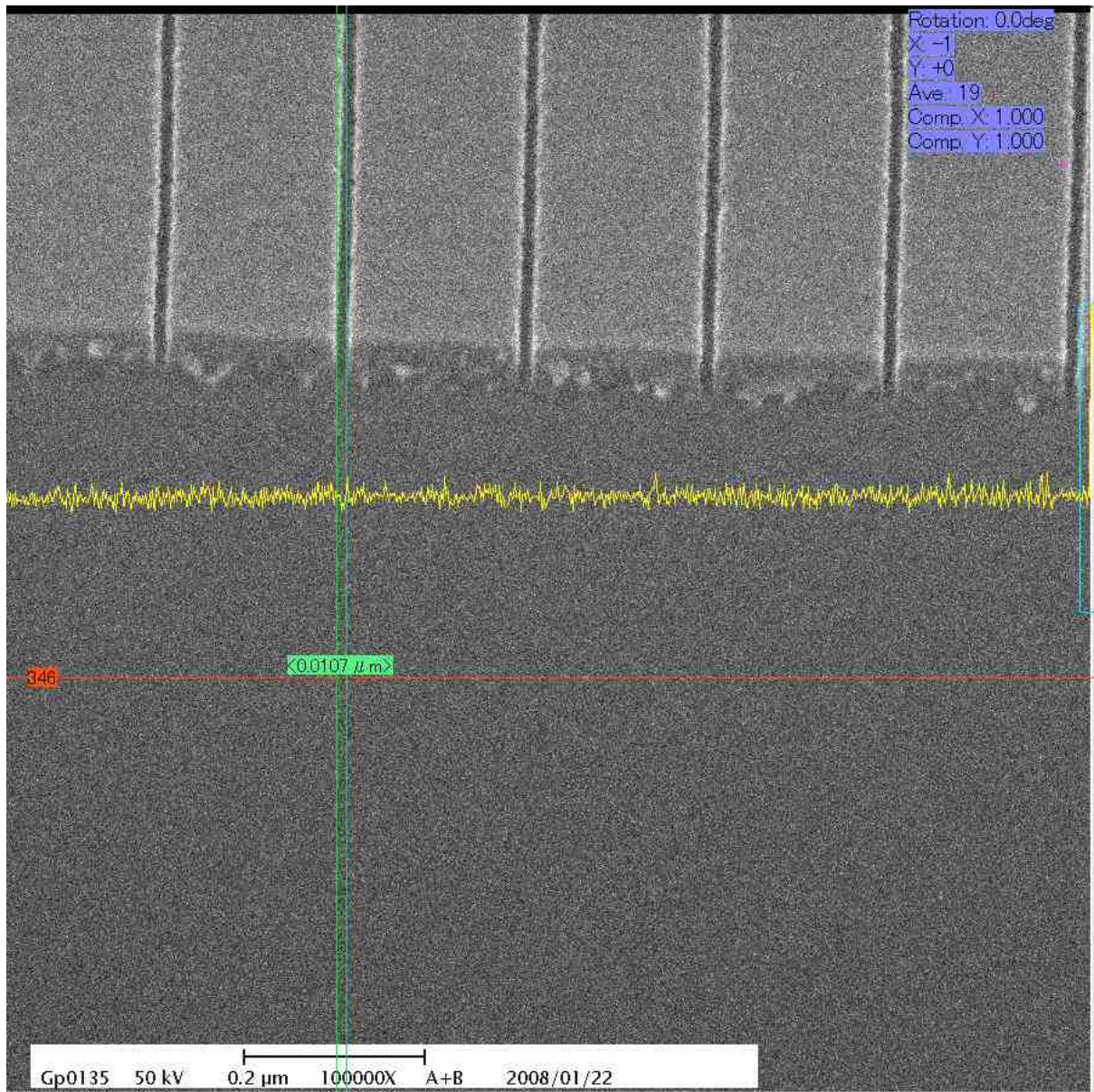
ACCEL. VOLT.	<u>50</u>	<u>kV</u>	EXT.VOLTAGE	<u>3.9</u>	<u>kV</u>
Emission CURR.	<u>68</u>	<u>uA</u>	CATHODE HEAT.	<u>2.31</u>	<u>A</u>
BEAM CURR.	<u>18</u>	<u>pA</u>	OL APERTURE	<u>0.04</u>	<u>mm</u>
FIELD SIZE	<u>0.075</u>	<u>mm</u>	Dot Map	<u>60000</u>	<u>dot</u>
DOSE TIME	<u>2.6</u>	<u>usec/dot</u>	RESIST NAME	<u>ZEP-520A</u>	
SUBSTRATE	<u>Si wafer</u>		RESIST THICKNESS	<u>0.08</u>	<u>μm</u>
Development temp	<u>room temp</u>		Development time	<u>7</u>	<u>sec</u>











0.1 μ m LINE & SPACE

ACCEL. VOLT.	<u>50</u>	<u>kV</u>	EXT.VOLTAGE	<u>3.9</u>	<u>kV</u>
Emission CURR.	<u>68</u>	<u>uA</u>	CATHODE HEAT.	<u>2.31</u>	<u>A</u>
BEAM CURR.	<u>100</u>	<u>pA</u>	OL APERTURE	<u>0.03</u>	<u>mm</u>
FIELD SIZE	<u>0.6</u>	<u>mm</u>	Dot Map	<u>60000</u>	<u>dot</u>
DOSE TIME	<u>0.9</u>	<u>usec/dot</u>	RESIST NAME	<u>ZEP-520A</u>	
SUBSTRATE	<u>Si wafer</u>		RESIST THICKNESS	<u>0.30</u>	<u>um</u>
Development temp	<u>room temp</u>		Development time	<u>300</u>	<u>sec</u>

